

APPROVAL SHEET

AMBPF Series – 2012(0805)- RoHS Compliance

MULTILAYER CERAMIC BAND PASS FILTER

Halogens Free Product

2.4 GHz ISM Band RF Application

Automotive

Qualified to AEC-Q200

Preliminary

P/N: AMBPF2008A17T

*Contents in this sheet are subject to change without prior notice.

FEATURES

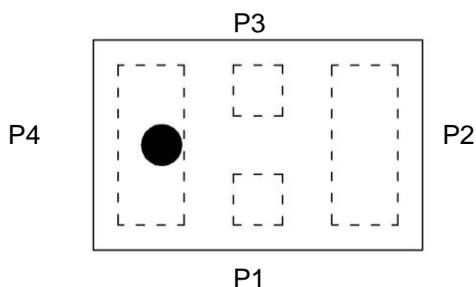
1. Miniature footprint: 2.0 X 1.2 X 0.8 mm³
2. LTCC Process
3. High Rejection on GSM Bands
4. High attenuation on 2nd and 3rd harmonic suppressed
5. LTCC process

APPLICATIONS

1. 2.4GHz ISM band RF applications
2. Bluetooth, Wireless LAN 802.11b/g/n, HomeRF

CONSTRUCTION

Top view



PIN	Connection
1	Input
2	GND
3	Output
4	GND

DIMENSIONS

Figure	Symbol	Dimension (mm)
Top view	L	2.00 ± 0.15
	W	1.25 ± 0.10
	T	0.80 ± 0.10
Side view	A	0.15 ± 0.10
	B	0.40 ± 0.05
Bottom view	C	0.30 ± 0.10
	D	0.30 ± 0.05
	E	0.15 ± 0.10
	F	0.95 ± 0.10
	G	0.30 ± 0.10
	H	0.35 ± 0.10

ELECTRICAL CHARACTERISTICS

AMBPF2008A17T	Specification
Frequency range	2412~2484 MHz
Insertion Loss	1.35 dB max. at +25°C 1.65 dB max. at -55°C ~ +125°C
Attenuation	30dB min. @ 804~ 828 MHz 20dB min. @ 1608~1656 MHz 30dB min. @ 3216~ 3312 MHz 38dB min. @ 4020~ 4140 MHz 20dB min. @ 4824~ 4968 MHz 20dB min. @ 5628 ~ 5796 MHz 20dB min. @ 6432 ~ 6624 MHz 35dB min. @ 7200 ~ 7500 MHz 20dB min. @ 7500 ~ 10000 MHz
VSWR	2.0 max.
Impedance	50Ω
Moisture sensitivity levels	LEVEL 1 (Refer to : IPC/JEDEC J-STD-020)

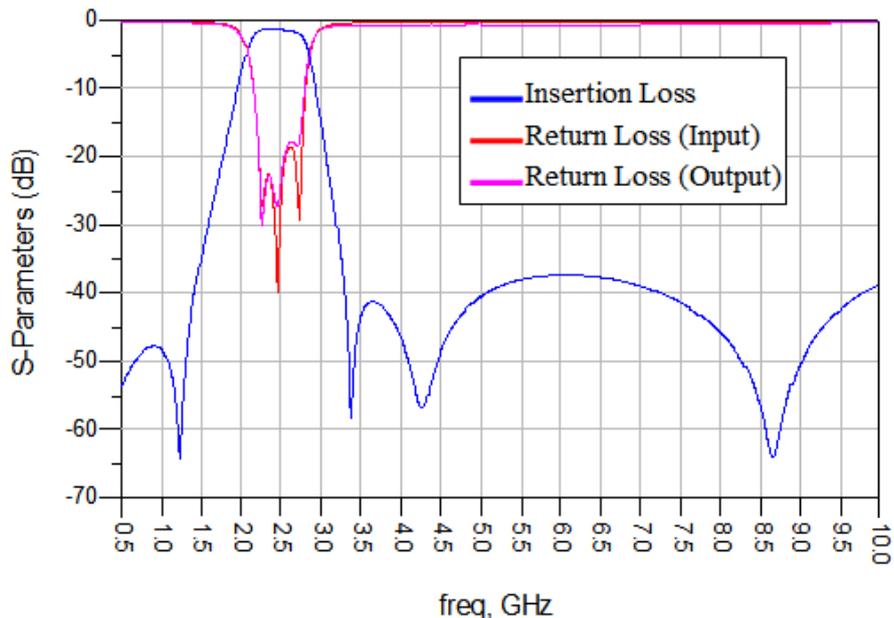
Operating & Storage Condition (Component)

Operation Temperature Range: -55°C ~ +125°C
Storage Temperature Range: -55°C ~ +125°C

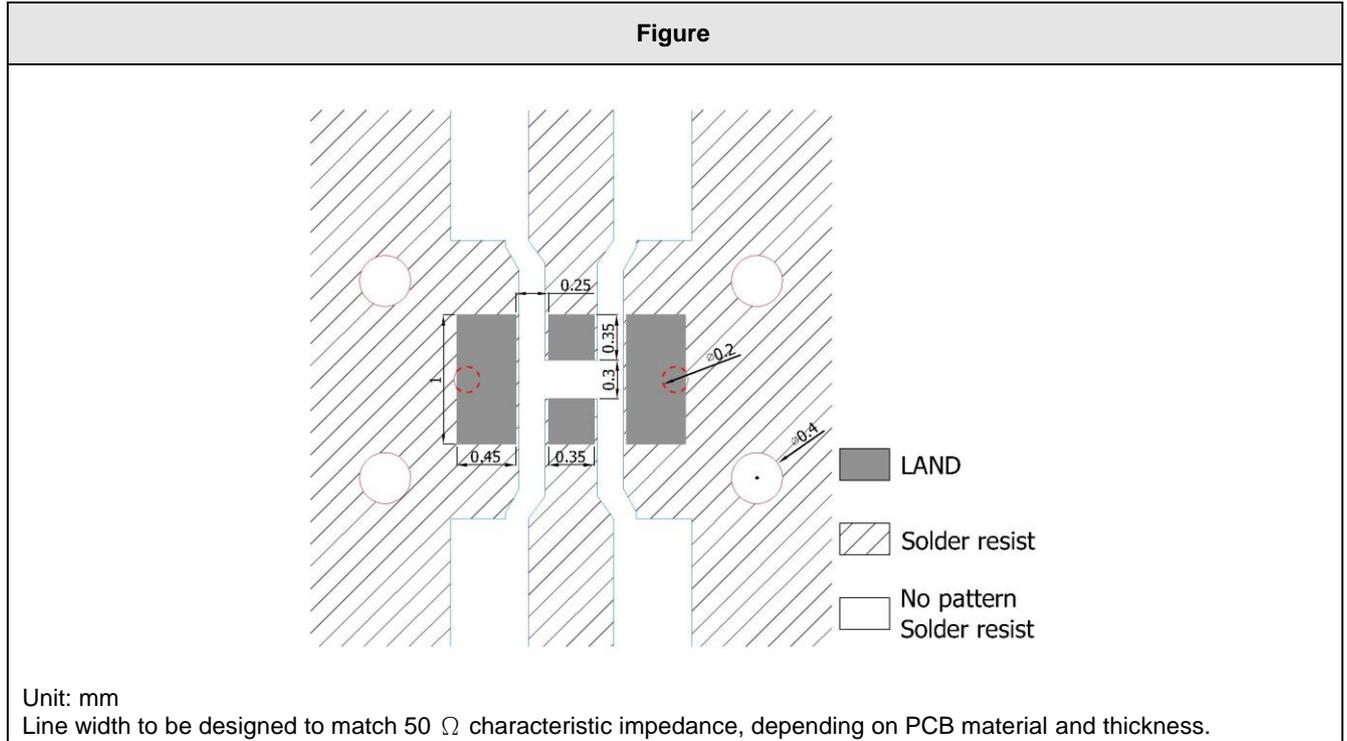
Storage Condition before Soldering (Included packaging material)

Storage Temperature Range: +5 ~ +40 °C
Humidity: 30 to 70% relative humidity

Typical Electrical Chart



SOLDER LAND PATTERN



RELIABILITY TEST

TEST	PROCEDURE / TEST METHOD	REQUIREMENT
Resistance to soldering heat (R.S.H) MIL-STD-202 method 210	Un-mounted chips completely immersed for 10±1 second in a SAC solder bath at 270°C±5°C	No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within -55 ~ 125°C. Loss of metallization on the edges of each electrode shall not exceed 25
Solderability J-STD-002	a)4hrs / 155°C *dry then solder dipping 235°C/5sec b)Steam 8 hrs then 215°C / 5sec solder dipping c)Steam 8 hrs then 260°C / 7sec solder dipping	95% coverage min., good tinning and no visible damage
Temperature cycling JESD22 method JA-104	1000 cycles, -55°C ~ +125°C, dwell time 30min	No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within -55 ~ 125°C.
Humidity MIL-STD-202 method 103	1000+48/-0 hours; 85°C, 85% RH	No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within -55 ~ 125°C.
High Temperature Exposure MIL-STD-202 method 108	1000+48/-0 hours; without load in a temperature chamber controlled 125±3°C	No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within -55 ~ 125°C.
Mechanical Shock MIL-STD-202 method 213	1/2 Sine Pulse / 100g Peak / Velocity 12.3ft/sec	No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within -55 ~ 125°C.
Board Flex AEC-Q200-005	RF component mounted on a 90mm glass epoxy resin PCB(FR4), bending once 2mm for 60sec	No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within -55 ~ 125°C.
Terminal strength AEC-Q200-006	Pressurizing force: 1.8Kg, Test time: 60±1sec. Only 0402 for 1.0kg/60sec	No remarkable damage or removal of the terminations
Vibration MIL-STD-202 method 204	Test 5g's for 20min., 12 cycles each of 3 orientations	No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within -55 ~ 125°C.
ESD AEC-Q200-002	Test contact 1.0KV (0.5KV for 1005 only)	No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within -55 ~ 125°C.

SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2,

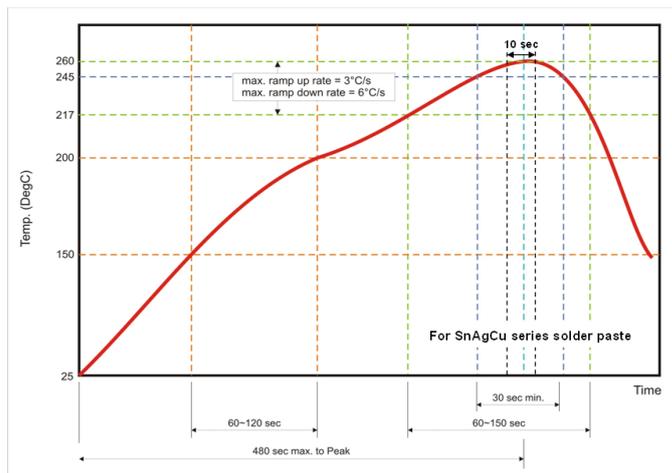


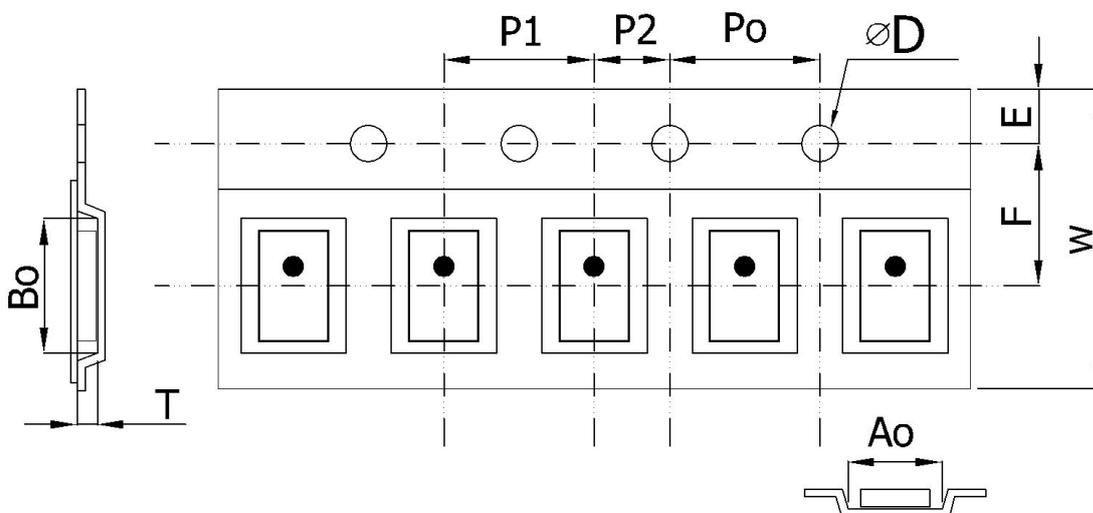
Fig 2. Infrared soldering profile

ORDERING CODE

AM Walsin Automotive device	BPF Product Code BPF : Band Pass Filter	20 Dimension code Per 2 digits of Length, Width,; e.g. : 20 = Length 20, Width 12,	08 Dimension code 08= Thickness 08	A Application A : 2.4GHz ISM Band	17 Specification Design code	T Packing T : Reeled
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Minimum Ordering Quantity: 2000 pcs per reel.

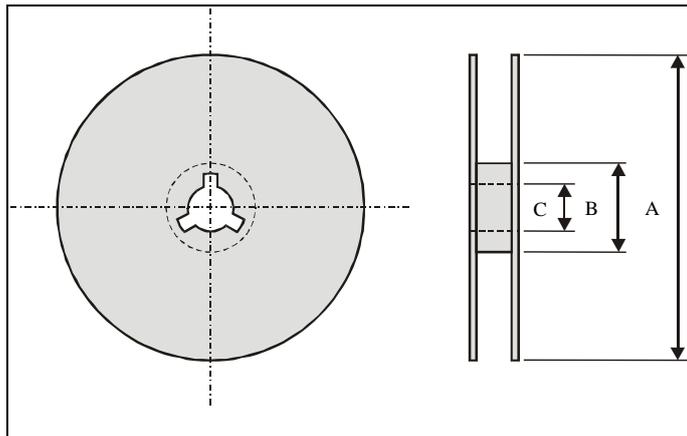
PACKAGING



Plastic Tape specifications (unit :mm)

Index	Ao	Bo	φD	T	W
Dimension (mm)	1.42 ± 0.10	2.25 ± 0.10	1.55 ± 0.05	0.95 ± 0.10	8.0 ± 0.10
Index	E	F	Po	P1	P2
Dimension (mm)	1.75 ± 0.10	3.50 ± 0.05	4.00 ± 0.10	4.00 ± 0.10	2.00 ± 0.05

Reel dimensions



Index	A	B	C
Dimension (mm)	Φ178.0	Φ60.0	Φ13.0

Taping Quantity:2000 pieces per 7" reel

CAUTION OF HANDLING

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Disaster prevention / crime prevention equipment
- (6) Traffic signal equipment
- (7) Transportation equipment (vehicles, trains, ships, etc.)
- (8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

Storage condition

- (1) Products should be used in 6 months from the day of WALSIN outgoing inspection.
- (2) Storage environment condition.
 - Products should be storage in the warehouse on the following conditions.
 - Temperature : +5 to +40°C
 - Humidity : 30 to 70% relative humidity
 - Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
 - Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
 - Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
 - Products should be storage under the airtight packaged condition.